

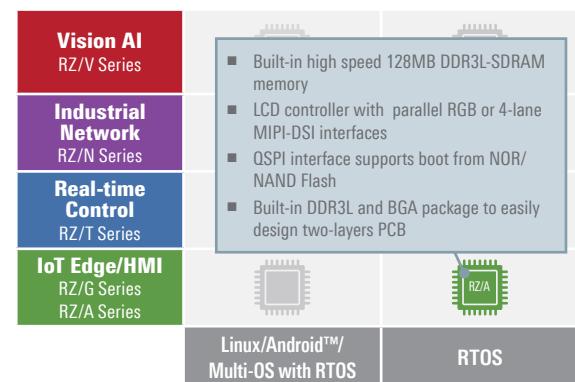
Optimize Speed and Graphics Performance for High-Definition HMIs

RENESAS RZ/A3M GROUP

64bit Arm® Cortex®-A55 MPU (1GHz) with built-in DDR3L SDRAM

The RZ/A3M MPUs based on the Arm® Cortex®-A55 (CA55) core with NEON™ extension and built-in large capacity 128MB DDR3L memory are equipped with a feature set optimized to address diverse human-machine interface (HMI) for consumer, smart home and building automation, healthcare, industrial applications, and office automation market segments.

The RZ/A3M MPUs also integrate features such as high-resolution Graphics LCD controller with parallel RGB and 4-lane MIPI-DSI interfaces to display panels, 2D graphics drawing engine, support QSPI NOR/NAND Flash for large-size programs, and 244 pin LFBGA package which is ideal for 2-layers board design.



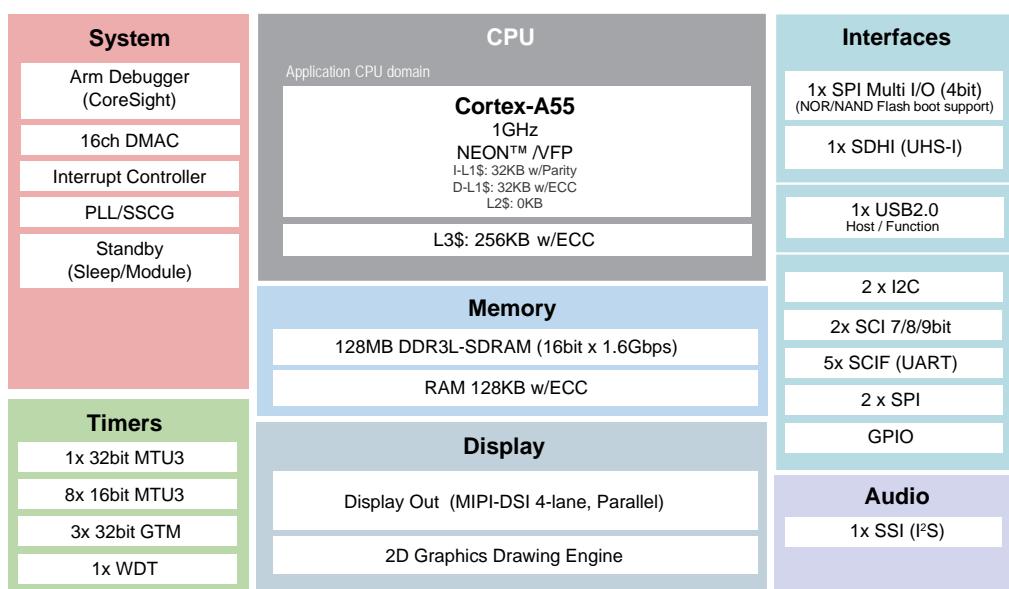
Features

- 64bit 1GHz Arm Cortex-A55 with NEON
- Built-in 128MB DDR3L SDRAM
- LCD controller up to WXGA (1280x800) with parallel RGB and MIPI-DSI (4lane) interface
- 2D Drawing engine
- QSPI NOR/NAND Flash boot
- Enable 2-layer PCB design
- SDHI for high-speed Wi-Fi® module
- I²S for audio interface
- USB 2.0 Interface for USB camera
- UART/SPI/I²C for sensors

Applications

- Consumer products
- Smart home and building automation
- Healthcare
- Industrial applications
- Office automation

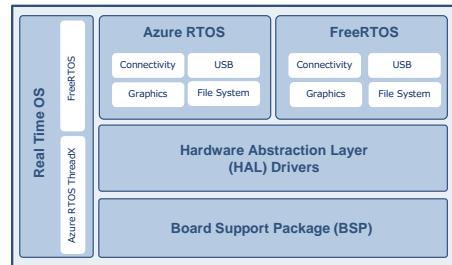
Block Diagram



Software Package

The Renesas RZ/A Flexible Software Package (FSP) is designed to provide easy-to-use, scalable, high-quality software for embedded system designs using RZ MPUs.

The FSP is based on an open software ecosystem of production-ready drivers, supporting FreeRTOS, Azure RTOS or bare-metal programming. It also includes a selection of other middleware stacks, providing great flexibility for migrating code from older systems or developing new applications from scratch.



Flexible Software Package (FSP)

Tools and Support

The e² studio IDE provides support with intuitive configurators and intelligent code generation to make programming and debugging easier and faster.

| | Renesas |
|---------------------------------|----------------------------|
| Development Environments | e ² studio |
| Compilers | GNU Arm Embedded Toolchain |
| ICEs | J-Link series from Segger |
| Supported RTOS | FreeRTOS, Azure RTOS |

Evaluation Kits

- Evaluate key features of RZ/A3M MPU and develop high-resolution HMI and other embedded systems applications
- Includes MIPI graphics expansion board (5inch TFT display, 720*1280 pixel)
- Features on-board debugging using SEGGER-J-Link
- Order the kit and download documentation, design package, development tools, and software at www.renesas.com/ek-rza3m
- Orderable part number: **RTK9EKZA3MS10001BE**



Ordering Information

| | R9A07G066M04GBG |
|------------------------|------------------------------------|
| CPU/Frequency | Cortex-A55/1.0GHz |
| RAM | 128MB DDR3L 128KB SRAM |
| Supported Flash | Quad SPI NOR/NAND Flash |
| LCD interface | Parallel/ MIPI 4-lane |
| Connectivity | 1xUSB2.0(Host/Device) 1xSDHI |
| T_j | -40 to 110°C |
| Package | BGA 244pin 17mm x 17mm 0.8mm pitch |

For more information, visit
www.renesas.com/RZA3M

